ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
1752-21.1	IPC Web Site for Information on IPC-1752 Standard				Form Type Distribute	Form Type * Declaration Class *				erials and M	Ifg Info	ormation					
Supplier	r Informa	tion															
Company	name*			Company un	Company unique ID			Unique ID Authority					Respon	Response Date*			
onsemi													2024-05	2024-05-11			
Contact Name				Title - Conta	Title - Contact			Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards				Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com				
Authorized Representative*				Title - Representative				Phone - Representative*				Email -	Email - Representative*				
Product-I	Env-Steward	ls		Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name			Effective D	Pate \	Version	N	Manufacturing Site		Weight	t*	UOM	Unit Type		
	MT9P00 DR		01I12-N4005-	2-N4005- 5 MP 1/2.5 CIS			2024-05-11	I		N	MY5		259.0		mg	Each	
Manufacturing Process Information																	
	Terminal Plating / Grid Array Material T		Terminal Base Alloy J-S		J-STD-020 MS	SL Rating Peal		eak Process Body Temperature		ure Max Time at Peak Temper		mperature Number of Reflow Cycles		S			
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 4		4		260			С	30	secoi	nds 3	3			
Comments												<u> </u>					
For more	information	regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	led
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybrominated Biphenyls (Pl	aterial for Cadmium and quantity limit of 0.1% by BB), Polybrominated Diphenyl Ethers (PBDE), an		
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the company that the company tha	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit ide in you believe may apply. If the part is an assembly is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per	the definition above except for defined Ro	oHS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	59.5	mg		Misc.	proprietary data		0.2261	mg
			Supplier	Silicon (Si)	7440-21-3		58.6848	mg
			Supplier	Aluminum (Al)	7429-90-5		0.589	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
Imaging Lens	55.3	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.765	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.765	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.765	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.765	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2765	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.765	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.765	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.4335	mg
Lid Attach	2.4	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.7584	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1248	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.7584	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.7584	mg
Mold Compound-Black	55.0	mg		Phenolic Resin	proprietary data		2.765 mg 2.765 mg 2.765 mg 0.2765 mg 2.765 mg 2.765 mg 38.4335 mg 0.7584 mg 0.7584 mg 0.7584 mg 0.7584 mg 0.7584 mg 0.7584 mg 0.55 mg 1.65 mg 0.55 mg 35.2 mg 1.1 mg 17.8632 mg	
			Supplier	Oxirane	39817-09-9		8.25	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.65	mg
			Supplier	Carbon Black (C)	1333-86-4		0.55	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.2	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1	mg
Substrate and Solder Mask	84.3	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		17.8632	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1043	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2782	mg
			Supplier	Acetophenone Derivative	Proprietary Data		1.6523	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2782	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2782	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	8.194	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.3046	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	2.8325	mg
			Supplier	Copper (Cu)	7440-50-8	39.9666	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.548	mg
Wire Bond - Au	0.3	mg	Supplier	Gold (Au)	7440-57-5	0.3	mg